



SPECIFICATION

(Reference sheet)

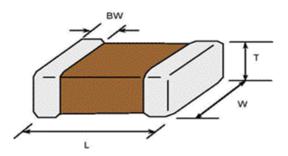
- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : CL100
 Description : CAP,
- CL10C101JB8NNNC CAP, 100pF, 50V, ± 5%, C0G, 0603

A. Samsung Part Number

		<u>CL</u> ①	<u>10</u> ②	<u>C</u> 3	<u>101</u> ④	<u>၂</u> (5)	<u>B</u> 6	<mark>8</mark> 7	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<mark>C</mark> 10
1	Series	Samsung Multi-layer Ceramic Capacitor										
2	Size	0603 (inch co	de)		L: 1.60 ± 0.10 mm			W:	0.80 ± 0.10 mm			
-	Dielectric Capacitance	C0G 100 pF				8	Inner Term					Ni Cu
	Capacitance	± 5 %					Platir		,,,,			Sn 100% (Pb Free)
	tolerance					9	Produ	uct				Normal
6	Rated Voltage	50 V				10	Speci	ial				Reserved for future use
\bigcirc	Thickness	0.80 ± 0.10 mm				1	Packa	aging				Cardboard Type, 7" reel

B. Structure and dimension



Samsung P/N	Dimension(mm)								
(Lead Free)	L	W	Т	BW					
CL10C101JB8NNNC	1.60 ± 0.10	0.80 ± 0.10	0.80 ± 0.10	0.30 ± 0.20					

C. Samsung Reliability Test and Judgement condition

	Performance	Test condition					
Capacitance Within specified tolerance		1Mb±10% 0.5~5Vrms					
Q	1000 min						
Insulation	10,000Mohm or 500Mohm× <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is smaller						
Appearance	No abnormal exterior appearance	Microscope (´10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	C0G						
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)						
Adhesive Strength	No peeling shall be occur on the	500g×F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within $\pm 5\%$ or $\pm 0.5 \text{ pF}$ whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 $^{\circ}$ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger						
	Tan δ, IR : initial spec.						
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours ´ 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or ± 0.75 pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 200 min						
	IR : 500Mohm or 25Mohm × μF						
	Whichever is smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or $\pm 0.3 \text{ pF}$ whichever is larger	Max. operating temperature					
	Q : 350 min	1000+48/-0hrs					
	IR : 1,000Mohm or 50Mohm × μF						
	Whichever is smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Min. operating temperature \rightarrow 25 °C					
	Tan δ, IR : initial spec.	\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycle test					
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* The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.